

**Actel Hermetic Package Mechanical (Cavity, weight, Lid size and Heat Sink size) configuration**

Package	Devices	Cavity	Weight (grams)	Lid (mils)	Head Sink (mm)
CQ84	A1020B	Up	2.2	520x520	No
CQ84	RT1020B	Up	2.2	520x520	No
CQ84	RH1020B	Up	2.2	520x520	No
CQ84	A32100DX	Up	2.2	550x550	No
CQ132	A1425A	Up	5.8	650x650	No
CQ132	RT1425A	Up	5.8	650x650	No
CQ172	A1280A	Up	8.8	870x870	No
CQ172	RT1280A	Up	8.8	870x870	No
CQ172	RP1280A	Up	8.8	870x870	No
CQ172	A1280XL	-	-	870x870	-
CQ196	A1460A	Up	11.1	770x770	No
CQ196	RT1460A	Up	11.1	770x770	No
CQ208	A32200DX	Up	18.5	900x900	22.85x22.85x0.50
CQ208	A42MX36	Up	8.8	770x770	No
CQ208	A54SX16	Up	8.8	520x520	No
CQ208	A54SX32	Up	8.8	590x590	No
CQ208	A54SX32A	Up	8.8	720x720	No
CQ208	A54SX72A	Up	8.8	720x720	No
CQ208	RT54SX16	Up	8.8	590x590	No
CQ208	RT54SX32	Up	8.8	770x770	No
CQ208	RT54SX32S	Up	8.8	720x720	No
CQ208	RT54SX72S	Up	15.5	900x900	22.85x22.85x0.50
CQ256	A14100A	Up	13.0	860x860	No
CQ256	RT14100A	Up	13.0	860x860	No
CQ256	A42MX36	Down	13.0	770x770	No
CQ256	A54SX16	Up	15.0	520x520	18.29x18.29x0.50
CQ256	A54SX32	Up	14.5	590x590	12.07x12.70x0.50
CQ256	A54SX32A	Up	13.0	720x720	No
CQ256	A54SX72A	Up	13.0	720x720	No
CQ256	RT54SX16	Up	14.5	860x860	12.07x12.70x0.50
CQ256	RT54SX32	Up	15.8	860x860	18.29x18.29x0.50
CQ256	RT54SX32S	Up	13.0	720x720	No
CQ256	RT54SX72S	Up	20.2	900x900	22.86x22.86x0.50
PG84	A1010B (1.0u)	Up	8.0	690x690	No
PG84	A1010B (0.9u)	Up	8.0	690x690	No
PG84	A1020B (1.0u)	Up	8.0	690x690	No
PG84	A1020B (0.9u)	Up	8.0	690x690	No
PG100	A1225A	-	-	720x720	-
PG100	A1225XL	-	-	550x550	-
PG100	A1415A	-	-	590x590	-
PG132	A1240A	Up	11.0	720x720	No
PG132	A1240XL	Up	11.0	720x720	No
PG133	A1425A	Up	11.0	650x650	No
PG175	A1440A	Down	18.2	670x670	No
PG176	A1280A	Up	18.2	870x870	17.00x17.00 (inside of package)
PG176	RT1280A	Up	18.2	870x870	17.00x17.00 (inside of package)
PG176	RP1280A	Up	18.2	870x870	17.00x17.00 (inside of package)
PG176	A1280XL	-	-	870x870	-
PG207	A1460A	Down	24.5	770x770	No
PG257	A14100A	Down	27.3	860x860	No
CG624	A54SX72A	Up	13.2	720x720	No
CI624	CG624 Interposer	-	-	-	-

**Notes:**

- 1/... Device weights are approximate values. There might be slight variations from lot to lot and device to device. For high accuracy, weight the specific parts in use is recommended.  
CQFP package weights do not include the ceramic leadframe, therefore they are the approximate weights after devices are trim-and-formed.
- 2/... Dimensions for CQFPs are recorded as mean design dimensions (X,Y, and Z as thickness), tolerance shall be applied. The overall package thickness is "ceramic thickness + lid thickness (typical -0.60 mm) + HS (0.50mm if exist)".
- 3/... HS thickness is 0.50 mm and brazed to the surface of the ceramic substrate.
- 4/... Total HS thickness is 1.27 mm, with only 0.50 mm extended outside of the ceramic surface.
- 5/... Cavity down CQFPs have their lid on the bottom side when attached to PCBs.  
The trim-form mechanical samples for both 32200DX and MX36 are interchangeable, since the 32200DX HS is facing up.
- 6/... All CQFPs in the same group of configuration (like CQ208, cavity up, no HS) are interchangeable as trim-form mechanical samples.
- 7/... All CQFPs and CPGAs have their lids and heatsinks grounded to the ground plane within the packages.